

REVISIONS			
REV.	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	MAR 23/16	J. SI

FS1 - Z38 - X0Z6 - 60

**CONTACT PLATING OPTION**

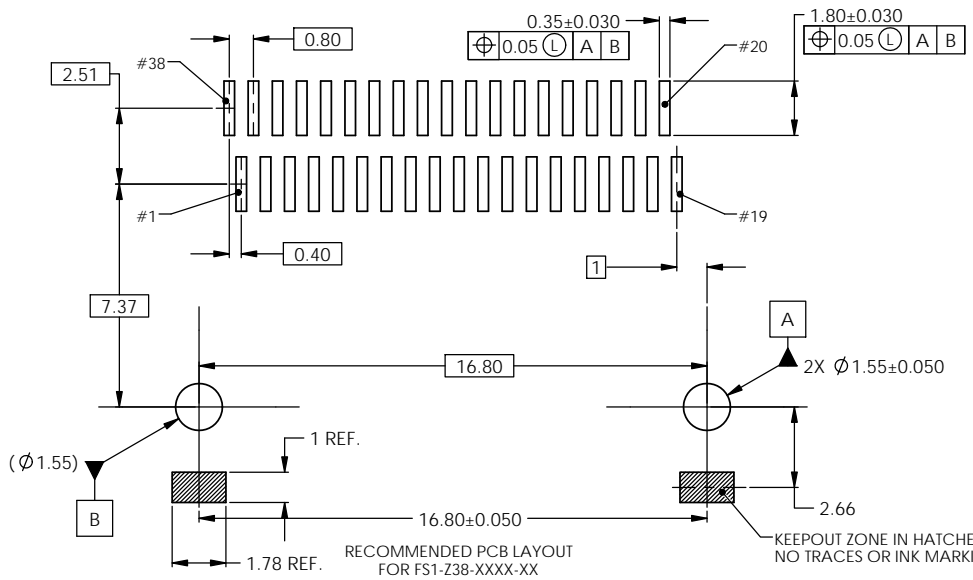
- 2** = 30 MICRO INCHES MINIMUM OF GOLD ON MATING END WITH 100 MICRO INCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50 MIN. MICRO INCHES OF NICKEL UNDER PLATE ALL OVER
- 3** = 15 MICRO INCHES MINIMUM OF GOLD ON MATING END WITH 100 MICRO INCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50 MIN. MICRO INCHES OF NICKEL UNDER PLATE ALL OVER

**NOTES:**

- 1) MATERIAL:  
HOUSING: SOLDER REFLOW PROCESS COMPATIBLE LCP, UL94V-0  
CONTACTS: PHOSPHOR BRONZE  
RESONANCE DAMPENING FEATURE: CONDUCTIVE POLYMER
- 2) ROHS COMPLIANT



DO NOT SCALE DRAWING



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UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:		APPROVALS	DATE	Amphenol High Speed Interconnects
.X ± 0.2	ANGLES ± 2°	DRAWN A. CHEN	MAR23/16	A Division of Amphenol Corp. www.amphenol-highspeed.com
XX ± 0.1		DESIGNED A. CHEN	MAR23/16	
MATERIAL AND FINISH		CHECKED J. SI	MAR23/16	UltraPort OSFP 4x28
		DRAWN J. PEN	MAR23/16	38 POSITION CONNECTOR
DRAWING NO.		DESIGNED ANDY CHEN	MAR23/16	
CODE IDENT NO. 03554		CHECKED J. SI	MAR23/16	
		DRAWN J. SI	MAR23/16	